

10GBASE-BX BIDI XFP 1330nm-TX/1270nm-RX 40km Transceiver

P/N: BIDI-XFP-ER-33



Features

- Up to 10.7Gbps Data Links
- Single Mode LC Receptacle Bi-directional Transceiver
- Up to 40km transmission on SMF
- Power dissipation<2W
- 1330nm DFB laser and 1270nm PIN receiver
- 2-wire interface with integrated Digital Diagnostic monitoring
- EEPROM with Serial ID Functionality
- Compliant with FC_PI_4 REV 7.0
- Compliant with XFP MSA with duplex LC connector
- Single + 3.3V Power Supply and LVTTTL Logic
- Operating case temperature: 0~+70°C

Applications

- 10GBASE-BX 10.3125Gb/s Ethernet
- 10GBASE-BX 9.953Gb/s Ethernet
- SONET OC-192 SR-1 SDH STM I-64.1

I. Absolute Maximum Ratings

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Storage Temperature	Ts	-40	-	85	°C	
Storage Ambient Humidity	HA	5	-	95	%	
Operating Relative Humidity	RH	-	-	85	%	
Power Supply Voltage	VCC	-0.3	-	4	V	
Signal Input Voltage	VCC	Vcc-0.3	-	Vcc+0.3	V	

II. Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note	
Ambient Operating Temperature	TA	0	-	70	°C	Without air flow	
Power Supply Voltage	VCC	3.14	3.3	3.47	V		
Power Supply Current	ICC	-	-	450	mA		
Data Rate	BR		10.3125		Gbps		
Transmission Distance	TD	2	-	20	km	Note (1)	
Coupled fiber		Single mode fiber					ITU-T G.652

Note (1). Measured with SMF

III. Specification of Transmitter

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note	
Average Launched Power	PO	1	-	5	dBm		
Average Launched Power(Laser Off)	POUT-OFF	-	-	-30	dBm	Note (1)	
Optical Modulation Amplitude	OMA	-3	-	-	dBm	Note (1)	
Center Wavelength Range	λ_C	1320	1330	1340	nm		
Side mode suppression ratio	SMSR	30	-	-	dB		
Spectrum Bandwidth(-20dB)	σ	-	-	1	nm		
Extinction Ratio	ER	3.5	6	-	dB	Note (2)	
Output Eye Mask		Compliant with FC_PI_4 REV 7.0					Note (2)

Note (1). The optical power is launched into SMF

Note (2). Measured with RPBS 2^31-1 test pattern @10.3125Gbs

IV. Specification of Receiver

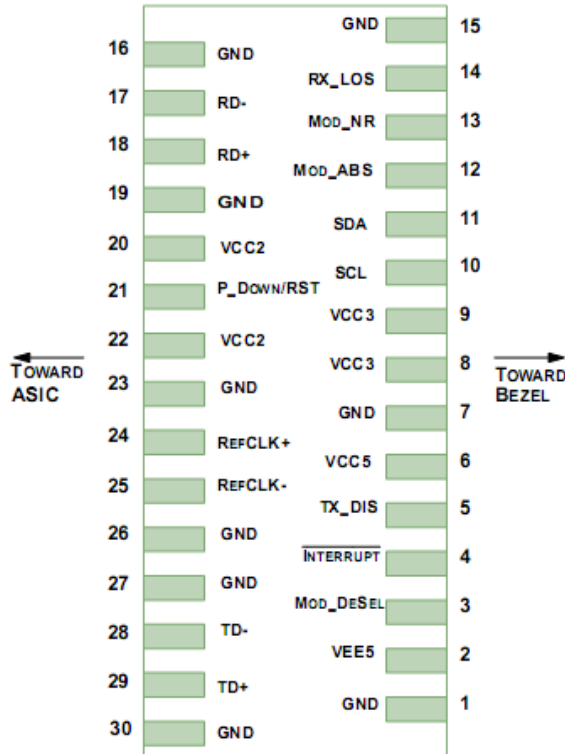
Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Input Optical Wavelength	λ_{IN}	1260	1270	1280	nm	
Receiver Sensitivity	PIN	-	-	-15	dBm	Note (1)
Input Saturation Power (Overload)	PSAT	0.5	-	-	dBm	Note (1)
LOS -Assert Power	PA	-28	-	-	dBm	
LOS -Deassert Power	PD	-	-	-16	dBm	
LOS -Hysteresis	PHys	0.5	-	4	dB	

Note (1). Measured with RPBS 2^31-1 test pattern @10.3125Gbs BER=<10^-12 ER=6DB

V. Electrical Interface Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Total power supply current	I _{cc}	-	-	580	mA	
Transmitter						
Differential Data Input Voltage	V _{DT}	120	-	820	mVp-p	
Differential line input Impedance	R _{IN}	85	100	115	Ohm	
Transmitter Fault Output-High	V _{FaultH}	2.4	-	V _{cc}	V	
Transmitter Fault Output-Low	V _{FaultL}	-0.3	-	0.8	V	
Transmitter Disable Voltage- High	V _{DisH}	2	-	V _{cc} +0.3	V	
Transmitter Disable Voltage- low	V _{DisL}	-0.3	-	0.8	V	
Receiver						
Differential Data Output Voltage	V _{DR}	300	-	850	mVp-p	
Differential line Output Impedance	R _{OUT}	80	100	120	Ohm	
Receiver LOS Pull up Resistor	R _{LOS}	4.7	-	10	KOhm	
Data Output Rise/Fall time	t _r /t _f	20	-	-	ps	
LOS Output Voltage-High	V _{LOSH}	2	-	V _{cc}	V	
LOS Output Voltage-Low	V _{LOSL}	-0.3	-	0.4	V	

VI. Description



Pin	Logic	Symbol	Name/Description	Note
1		GND	Module Ground	1
2		VEE5	Optional -5.2 Power Supply – Not required	

3	LVTTL-I	Mod-Desel	Module De-select; When held low allows the module to respond to 2-wire serial interface commands	
4	LVTTL-O	Interrupt	Interrupt (bar); Indicates presence of an important condition which can be read over the serial 2-wire interface	2
5	LVTTL-I	TX_DIS	Transmitter Disable; Transmitter laser source turned off	
6		VCC5	+5 Power Supply	
7		GND	Module Ground	1
8		VCC3	+3.3V Power Supply	
9		VCC3	+3.3V Power Supply	
10	LVTTL-I	SCL	Serial 2-wire interface clock	2
11	LVTTLI/O	SDA	Serial 2-wire interface data line	2
12	LVTTL-O	Mod_Abs	Module Absent; Indicates module is not present. Grounded in the module.	2
13	LVTTL-O	Mod_NR	Module Not Ready; XGIGA defines it as a logical OR between RX_LOS and Loss of Lock in TX/RX.	2
14	LVTTL-O	RX_LOS	Receiver Loss of Signal indicator	2
15		GND	Module Ground	1
16		GND	Module Ground	1
17	CML-O	RD-	Receiver inverted data output	
18	CML-O	RD+	Receiver non-inverted data output	
19		GND	Module Ground	1
20		VCC2	+1.8V Power Supply – Not required	
21	LVTTL-I	P_Down/RST	Power Down; When high, places the module in the low power stand-by mode and on the falling edge of P_Down initiates a module reset	
			Reset; The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle.	
22		VCC2	+1.8V Power Supply – Not required	
23		GND	Module Ground	1
24	PECL-I	RefCLK+	Reference Clock non-inverted input, AC coupled on the host board – Not required	3
25	PECL-I	RefCLK-	Reference Clock inverted input, AC coupled on the host board – Not required	3
26		GND	Module Ground	1
27		GND	Module Ground	1
28	CML-I	TD-	Transmitter inverted data input	
29	CML-I	TD+	Transmitter non-inverted data input	
30		GND	Module Ground	1

Notes:

1. Module circuit ground is isolated from module chassis ground within the module.
2. Open collector; should be pulled up with 4.7k – 10kohms on host board to a voltage between 3.15V and 3.6V.
3. A Reference Clock input is not required by the XFP-10GER. If present, it will be ignored.

VII. Ordering information

Part Number	Product Description
BIDI-XFP-ER-33	BIDI XFP, 10Gbps, 1330nm, SMF, 40KM, DDM, LC connector, 0°C ~ +70°C
BIDI-XFP-ER-27	BIDI XFP, 10Gbps, 1270nm, SMF ,40KM, DDM, LC connector, 0°C ~ +70°C